

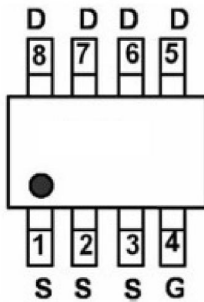
FEATURES

- $R_{DS(ON)} \leq 55m\Omega$ (43m Ω Typ.) @ $V_{GS} = -10V$
- $R_{DS(ON)} \leq 90m\Omega$ (55m Ω Typ.) @ $V_{GS} = -4.5V$

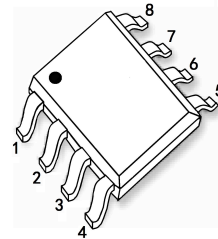
APPLICATIONS

- PWM Applications
- Load Switch
- Power Management

PIN ASSIGNMENT

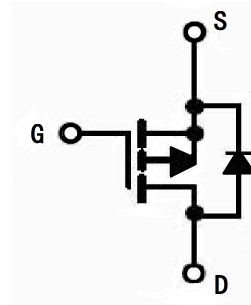


SOP-8



1: S	3: S	5: D	7: D
2: S	4: G	6: D	8: D

P-CHANNEL MOSFET



Absolute maximum ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Max.	Units
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	-5.1
		$T_C = 100^\circ C$	-3.2
I_{DM}	Pulsed Drain Current ^{note1}	-20	A
P_D	Power Dissipation	$T_A = 25^\circ C$	2.5
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	50	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$

Electrical characteristics (T_a=25 °C, unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} = 0V,	-	-	-1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.35	-2	V
R _{DS(on)}	Static Drain-Source on-Resistance <small>note2</small>	V _{GS} = -10V, I _D = -5.1A	-	43	55	mΩ
		V _{GS} = -4.5V, I _D = -4.2A	-	55	90	
g _{FS}	Forward Transconductance	V _{DS} = -5V, I _D = -5.1A	4	-	-	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -15V, V _{GS} = 0V, f = 1.0MHz	-	980	-	pF
C _{oss}	Output Capacitance		-	390	-	pF
C _{riss}	Reverse Transfer Capacitance		-	135	-	pF
Q _g	Total Gate Charge	V _{DS} = -15V, I _D = -5.1A, V _{GS} = -10V	-	11	-	nC
Q _{gs}	Gate-Source Charge		-	2.0	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	2.8	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = -15V, I _D = -1A, V _{GS} = -10V, R _{GEN} =6Ω	-	14	-	ns
t _r	Turn-on Rise Time		-	12	-	ns
t _{d(off)}	Turn-off Delay Time		-	56	-	ns
t _f	Turn-off Fall Time		-	20	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-5.1	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-20	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -5.1A	-	-	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

Typical Characteristics

Figure 1: Output Characteristics

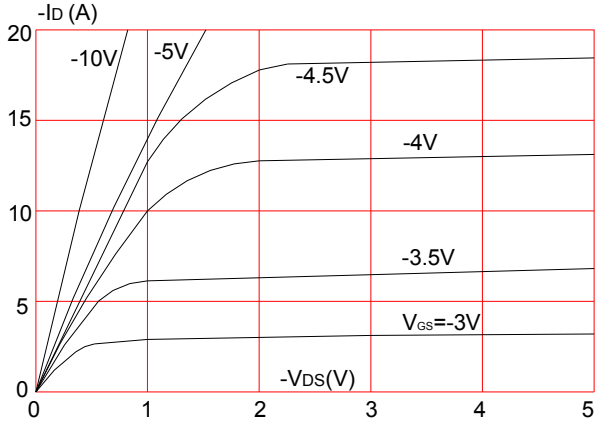


Figure 2: Typical Transfer Characteristics

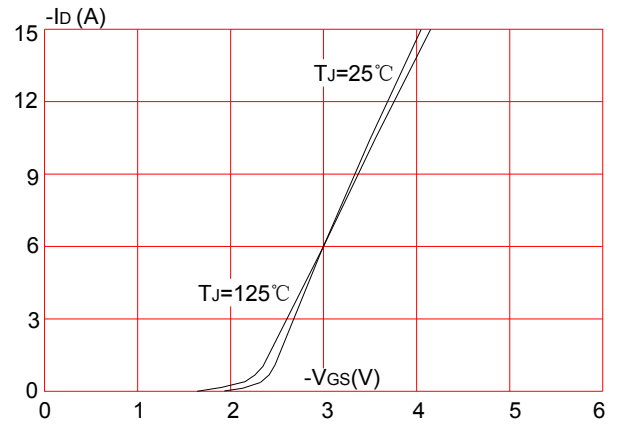


Figure 3: On-resistance vs. Drain Current

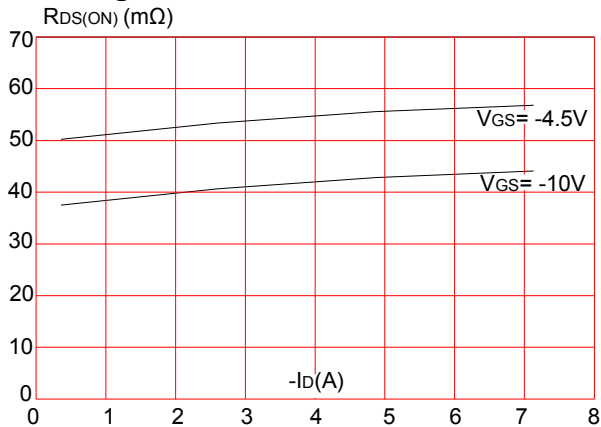


Figure 4: Body Diode Characteristics

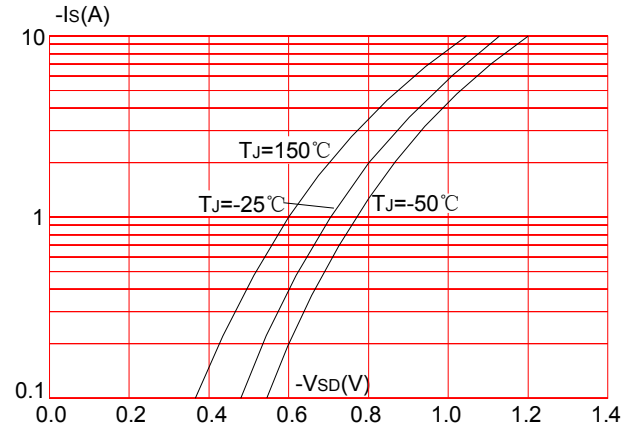


Figure 5: Gate Charge Characteristics

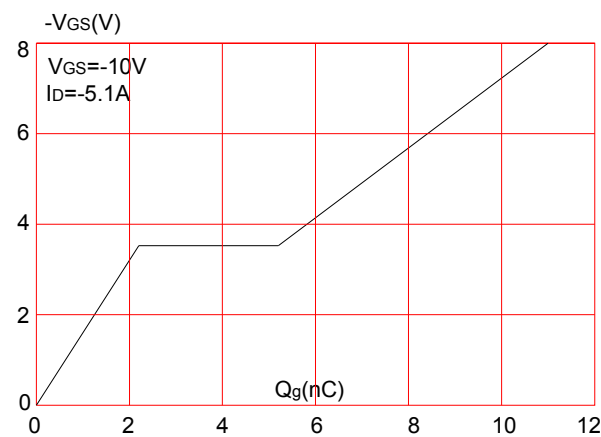
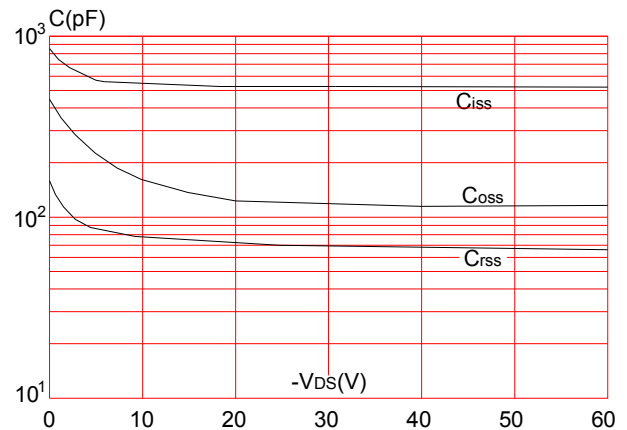


Figure 6: Capacitance Characteristics



Typical Characteristics

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

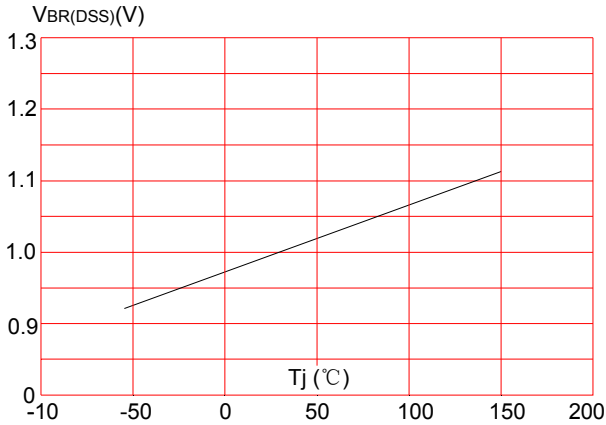


Figure 8: Normalized on Resistance vs. Junction Temperature

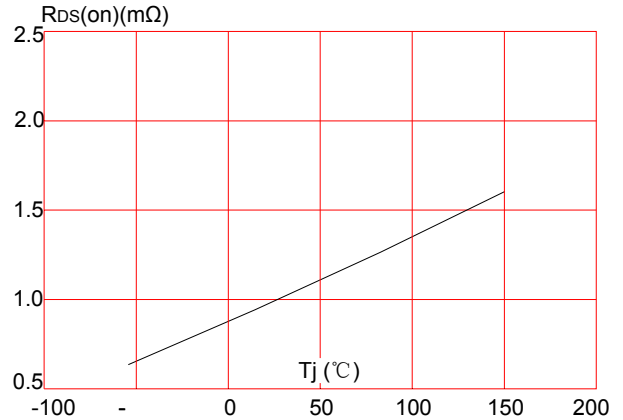


Figure 9: Maximum Safe Operating Area

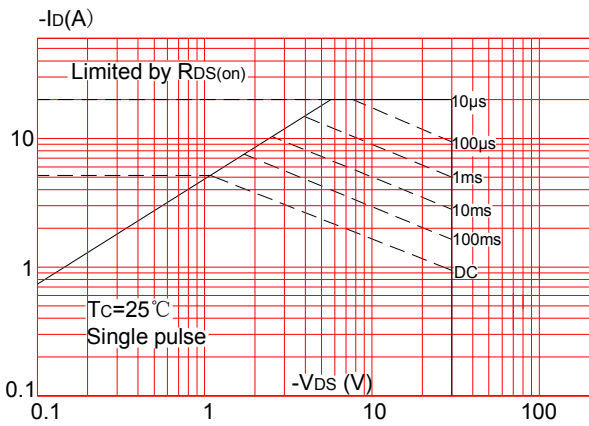


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

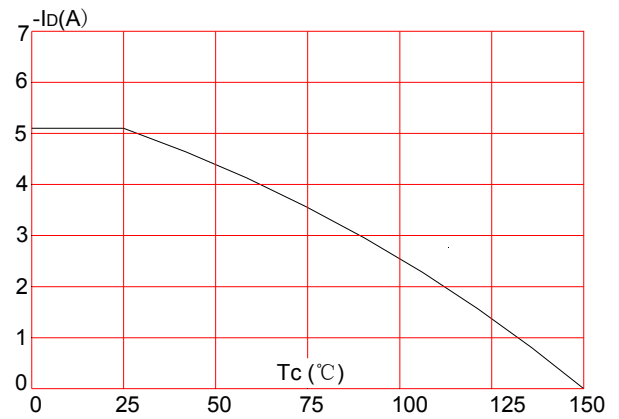
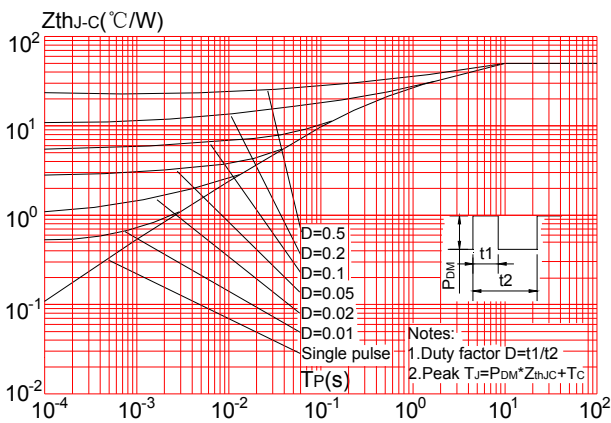
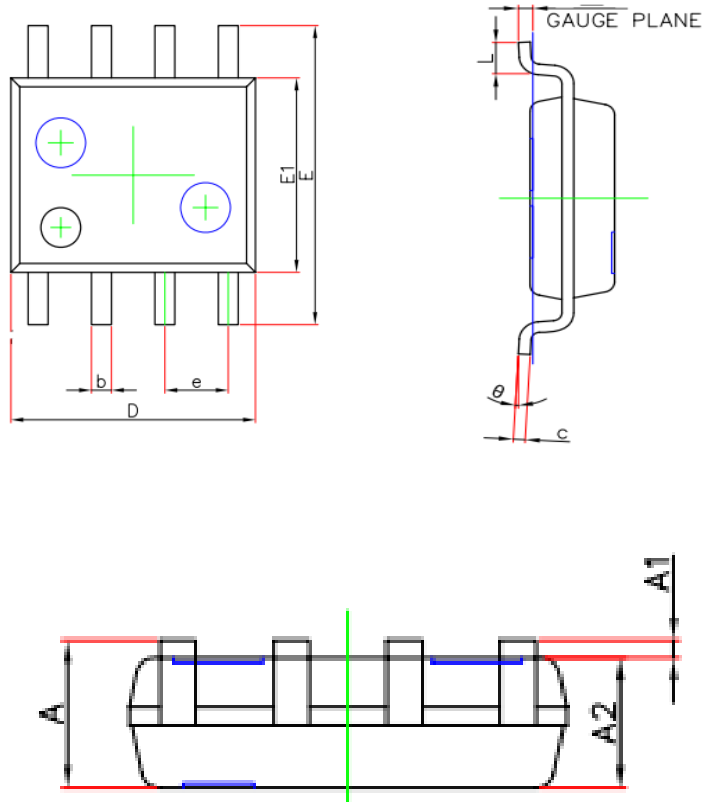


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient (SOP-8)



SOP-8 PACKAGE OUTLINE DRAWING



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E1	3.800	4.000	0.150	0.157
E	5.800	6.200	0.228	0.244
e	1.27(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°